

HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新案发行	YIN	Linson	Rambo	23-05-17

NOTES:

1.MATERIAL:

1.1 HOUSING: HIGH TEMPERATURE PLASTIC,
UL94V-0,COLOR:BLACK

1.2 CONTACT: Copper alloy

1.3 SOLDER PEG: STAINLESS STEEL

2.FINISH:

2.1 Contact: Au(see table) plated on contact area
G/F plated on solder area;

Nickel 50u"min underplating over all.

2.2 Solder peg: Matte Tin plated 80u"min,
and Nickel 50u"min underplating.

3.RECOMMENDED PCB THICKNESS: 0.8mm

4.DATE CODE:

YY: YEAR (23: 2023)

WW: WEEK (25: THE 25 WEEK)

5.DURABILITY: G/F~15u" Au 25CYCLES
30u" Au 60CYCLES.

SECTION A-A

Part NO.										R=PACK-R0335			
CF	5	F	67	12	M	X	X	X	X				

2

3

4

5

6

A

2

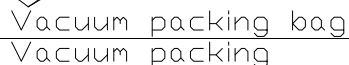
3

4

5

6



10

6. PEELING SPEED: 300 mm/min.

1



DIMENSIONS	
(METRIC)	(MM)

